

first surface of said plurality of circuit patterns is a line through which an electric current flows;

a via formed on said insulating layer, said via having one end opened on said first surface of said insulating layer and the other end closed by a circuit pattern of said plurality of circuit patterns formed on a part of said insulating layer other than said first surface;

a first plating layer having (1) a first portion that covers an inner surface of said via and a circuit pattern of said plurality of said circuit patterns that closes said other end of said via and which is exposed within said via, (2) a second portion that covers a circuit pattern of said plurality of said circuit patterns that is on said first surface and which continues to said one end of said via, and (3) a third portion that covers a part of said circuit pattern of said plurality of circuit patterns formed on the first surface at a location outside the via, wherein the first to third portions are simultaneously processed; and

a second plating layer laminated on said first plating layer and electrically connecting said circuit pattern of said plurality of circuit patterns formed on said first surface with said circuit pattern of the plurality of circuit patterns that closes said other end of said via, wherein the second plating layer and the third portion of the first plating layer form a thick portion having an increased thickness on a part of said circuit pattern formed on the first surface, and a current capacity of the circuit pattern is increased at the thick portion.

¹ A marked-up copy of Claim 1 is attached hereto.